

ABSTRACT OF THE DISCLOSURE

A semiconductor apparatus and method of manufacturing and an electronic apparatus are provided that achieve excellent productivity and substantially reduced manufacturing costs. The semiconductor apparatus may include a substrate main
5 body having a mounting surface for mounting the semiconductor device, a plurality of leads formed on the mounting surface and a plurality of conduction sections each defining at least a part of an external terminal. The conduction sections may be electrically connected to each of the leads.

G S O P B E S H E